Meeting the needs of the SMT Age





metal circuit boards exclusive use.

Soldering machine of metal circuit boards exclusive use RF-250N2

The RF-250N2 is a hot plate type reflow soldering machine with large heating capacity. Using far-infrared and hot-air heating, it can reflow solder difficult boards requiring large heating capacity such as ceramic and enamel boards, as well as steel, aluminum, and other metal circuit boards.

The carrier-bar (or Teflon sheet carrier) presses the circuit board to be soldered directly on top of the hot plate and slides it along. As the board is directly heated by the hot plate, even boards requiring high heat capacity can be efficiently reflow soldered in a short time and with high temperature precision.

Features

* 5 zone heating plate makes reflow soldering of enamel or metal circuit boards easy.

- * The RF-250N2 can reflow solder boards measuring up to 150×150×5mm.
- * 5 heating zones in lower section and 1 heating zone in upper section all have digital display and PID control. Full operation can be carried out with high precision at stable temperature.
- * With a heating range up to maximum 400°C, the RF-250N2 can perform high-temperature soldering of over 300°C.

Specifications Applicable circuit boards Heating section : 5 zones, (W)150×(L)1000×(H)40mm (at the inlet) Ceramic boards, enamel boards, metal Preheat section No.1 zone:(W)150×(L)200mm 1.3kW boards, multi layer printed circuit boards. No.2 zone:(W)150×(L)200mm 1.0kW Also, one-side-mounted SMT boards with No.3 zone:(W)150×(L)200mm 1.0kW large heat capacity. Reflow section No.4 zone:(W)150×(L)200mm 1.3kW+IR1.0kW • Dimensions :25mm×25mm to After heat section No.5 zone:(W)150×(L)200mm 1.0kW 150mm×150mm Heating method : Hot plate (Only the 4th zone is up IR heater used together.) • Board thickness :0.8mm to 5mm Temperature control: Max. 400°C, P.I.D. temperature controller. Height :Max. 40mm Conveyor : Carrier bar (metal fitting to push back of board) system Applications or Teflon sheet carrier system. · Reflow soldering of enamel or metal circuit Speed : 50 to 1000 mm/min boards. Speed controll : Digital type speed controller. · Soldering microchips on radiator or metal Direction : $R \rightarrow L \text{ or } L \rightarrow R$ (at user's request) block. Sensor : Thermocouple (CA) (Inside hot plate) • High-temperature soldering of over 300°C. Cooling : Forced cooling by a fan on the outlet side. Other heating operations for boards with : Single phase 220V About 7.5 kW, 50/60 Hz • Power supply large heat capacity. • N₂ supply quantity : About 20 to 100ℓ/min. Safety devices : Leak/Over-current circuit breaker, Limitations Emergency stop switch, Only one-side-mounted circuit boards can Alarm output (over/under temperature / heater disconnection) be treated. Torque limiter for chain conveyor · Can not process resin boards that warp • External dimensions: (W)1680×(D)550×(H)1070mm. when heated. • Weight : about 170kg Options • Operation indication lamp. * Specifications subject to change without notice. Main Office : 425-3 Inari-cho, Isesaki-city, Gunma 372-0804 Japan JAPAN PULSE LABORATORIES, INC. TEL 81-270-23-1031 FAX 81-270-23-1943 E-mail : info@jpl.com http://www.jpl.com/